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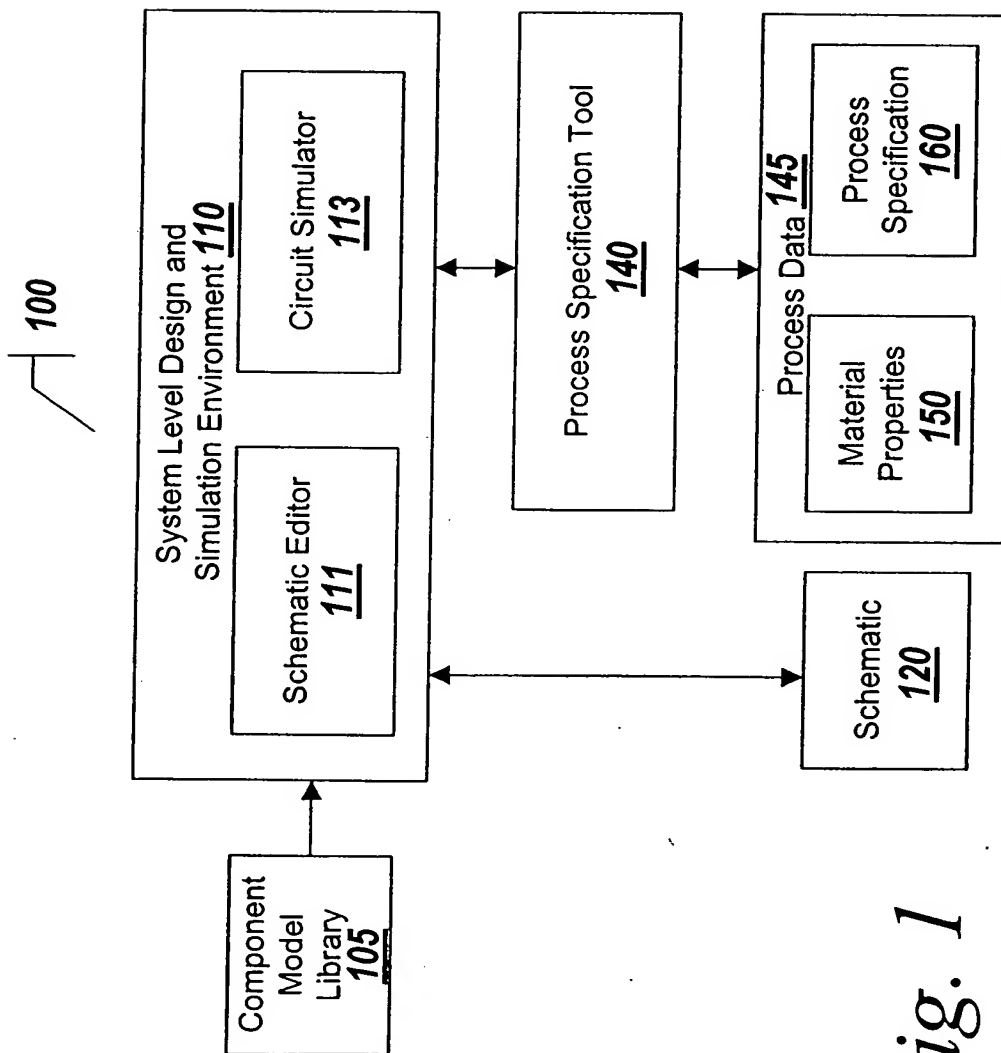


Fig. 1

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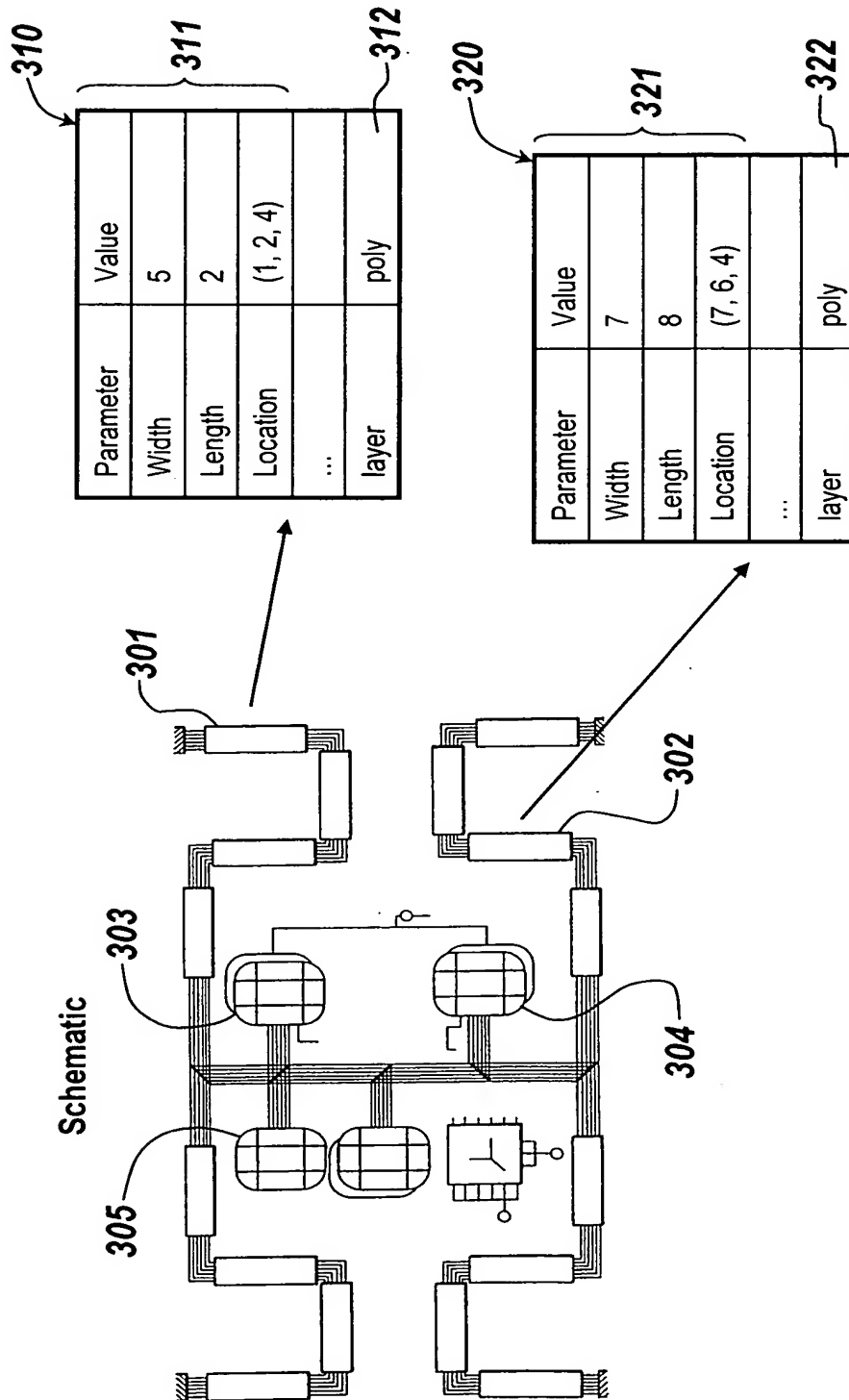


Fig. 2

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400

ProcessEditor: u:\Design_Files\BeamDesign\Devices\beam.proc

File Edit View Help

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Step	Action	Type	Layer Name	Material	Thickness	Color	Mask Name/ Polarity	Depth	Offset
0	Base		Substrate	SCILICON	10.0	cyan	GND		
1	Deposit	Stacked	Nitride	SIN	0.2	blue			
2	Deposit	Stacked	Sacrifice	BPSG	2.0	yellow			
3	Etch	Front, Last Layer				yellow	anchor	2.0	0.0
4	Deposit	Conformal	poly	POLYSILICON	0.5	red			
5	Etch	Front, Last Layer				red	beam	0.5	0.0
6	Deposit	Stacked	metal1	ALUMINUM(FILM)	1.0	green			
7	Etch	Front, Last Layer				cyan	met1	1.0	0.0
8	Deposit	Planar	metal2	GOLD	1.0	red			
9	Etch	Front, Last Layer				white	met2	1.0	0.0
10	Sacrifice			BPSG					

Fig. 3

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Close

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Edit Materials in u:\Design_Files\Shared\MPD\Impd1.mpd

New Material

Copy Material

Delete Material

Material	POLYSILICON
Fab Process	Thin_film
Elastic Contents	Elastic-iso
Density(kg/um ³)	Constant-Scalar
Stress(MPa)	Constant-Scalar
TCE(1/K)	Constant-Scalar
ThermalCond(pW/umK)	Constant-Scalar
SpecificHeat(pJ/kgK)	Constant-Scalar
ElectricCond(pS/um)	Constant-Scalar
Dielectric	Constant-Scalar
Viscosity(kg/um/s)	Constant-Scalar
PiezoResistiveCoeffs(1/MPa)	Constant_Scalar

Fig. 4

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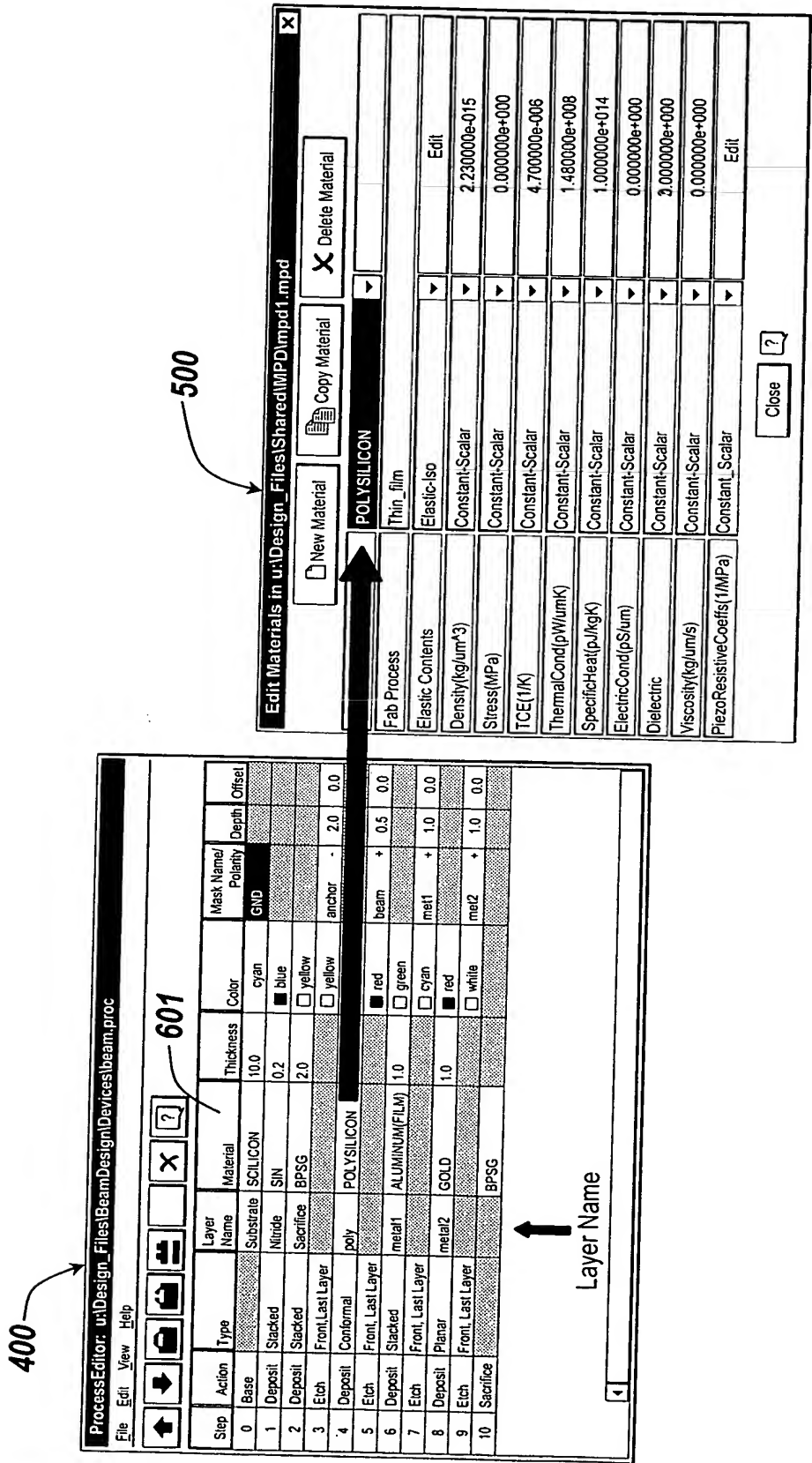
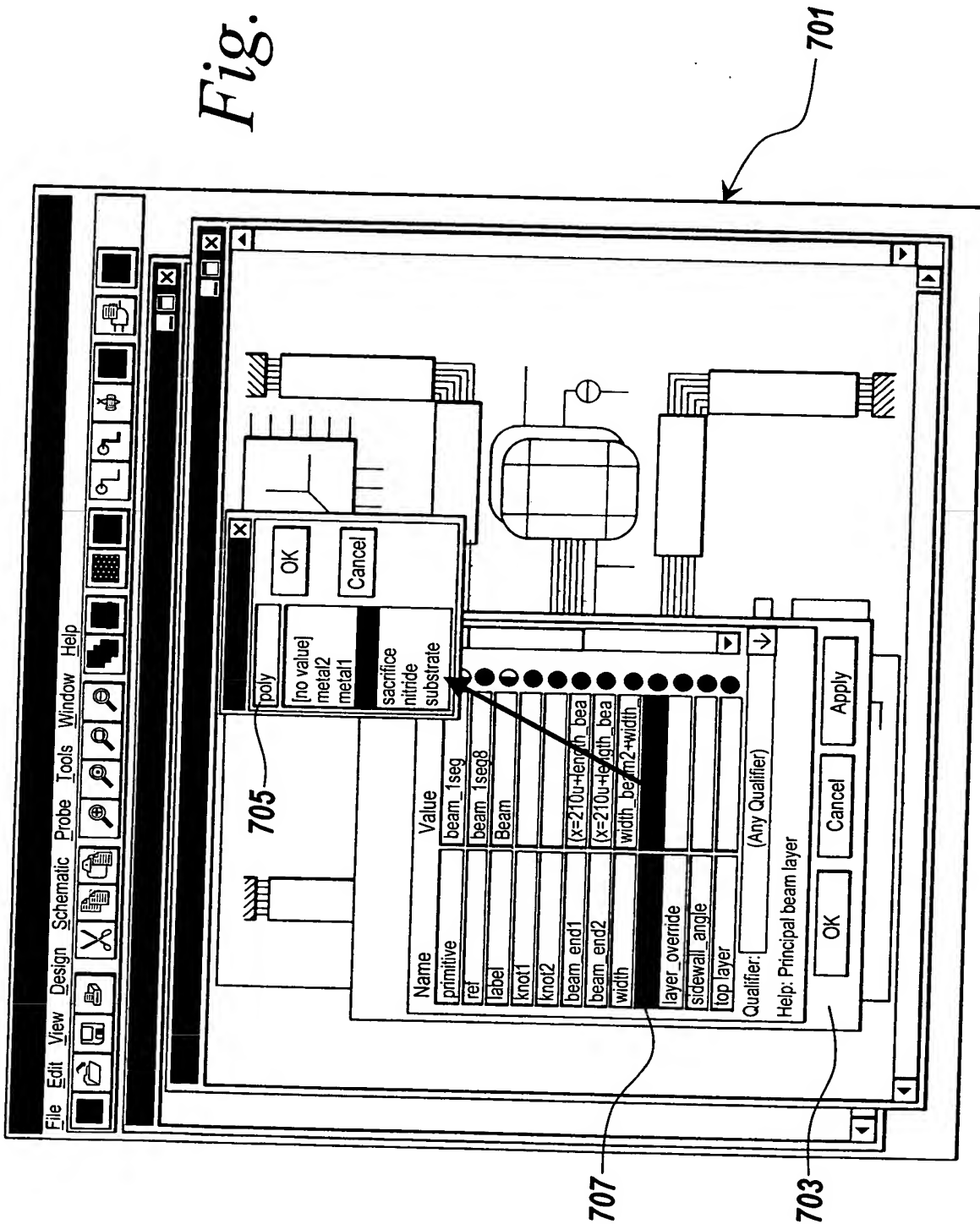


Fig. 5

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Fig. 6



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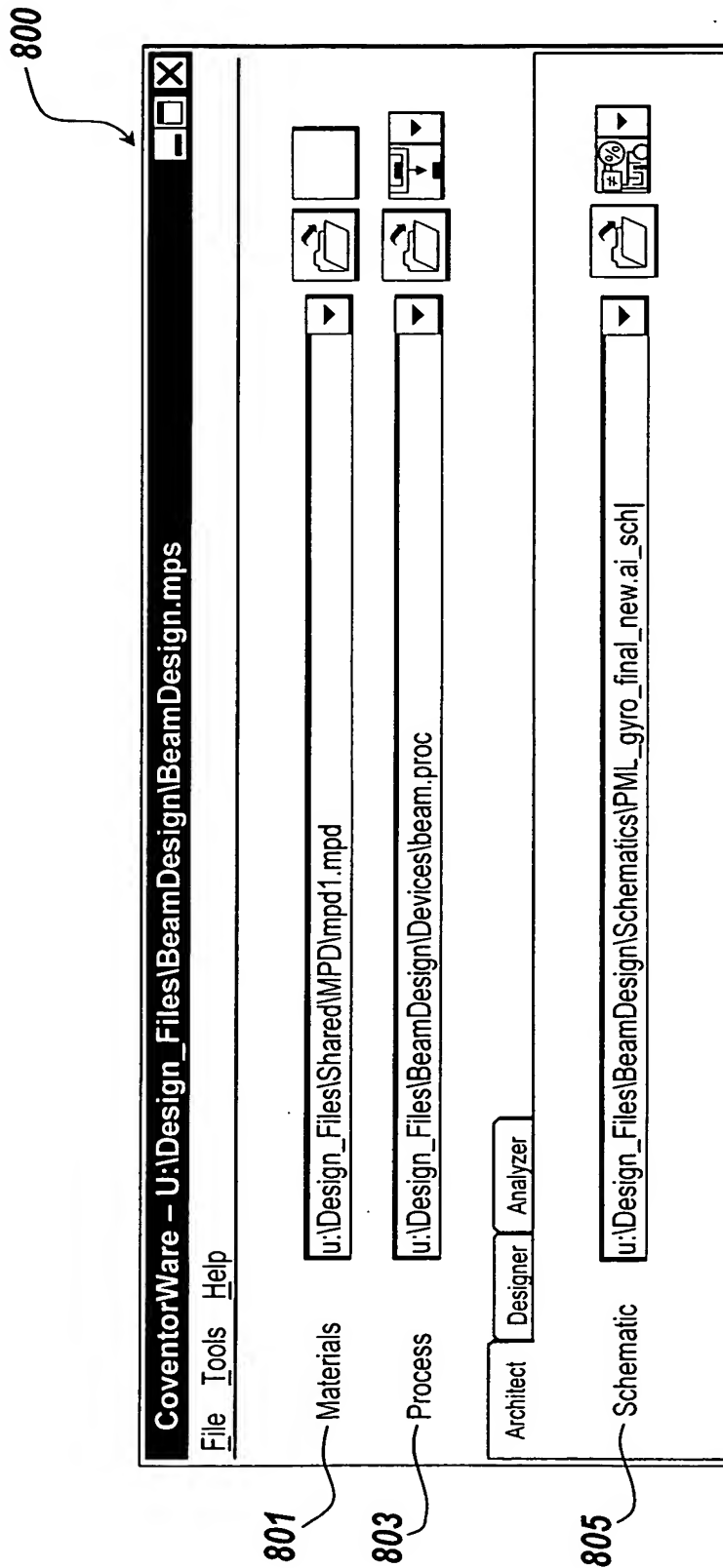


Fig. 7